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03/05/2002

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

See 1021

APPL NUM 10087742	FILING DATE 03/05/2002	CLASS 219	SUBCLASS 560	GAU 1725	742	EXAMINER Ip
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**APPLICANTS: Takaoka Hidekiyo; Maegawa Kiyotaka;

**CONTINUING DATA VERIFIED:
THIS APPLICATION IS A DIV OF 09/632,819 08/07/2000

** FOREIGN APPLICATIONS VERIFIED:

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PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO M1071-1711
TITLE : Lead-free solder and soldered article		

U.S. DEPT. OF COMM./PAT. & TM-PTO 435L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED F R ISSUE	Application Examiner	
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